12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20260421005.2
Qualification of TI Clark as an additional Assembly/Test site and TI CDAT as additional Test site for select devices
Change Notification / Sample Request

Date: April 22, 2026
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260421005.2
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	**CUSTOMER PART NUMBER**
DS90UB9722TRURRQ1	NULL
DS90UB984RURTQ1	NULL
DS90UH984RURTQ1	NULL
DS90UH988RURTQ1	NULL
DS90UB988RURTQ1	NULL
DS90UB9702TRURTQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260421005.2	**PCN Date:**	April 22, 2026
Title:	Qualification of TI Clark as an additional Assembly/Test site and TI CDAT as additional Test site for select devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	October 19, 2026	**Sample requests accepted until:**	June 21, 2026*

*Sample requests received after June 21, 2026 will not be supported.

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Material
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Clark as an additional Assembly/Test site and TI CDAT as additional Test site for select devices. Material differences between sites.

Additional A/T site

	Current A/T site		Additional A/T site
Assembly site	AP1	SCSAT	TI Clark
Mount compound	SID#101371420	SID#R008-0141X	4231301
Lead finish	NiPdAuAg	NiPdAuAg	NiPdAu

Some of the devices are currently tested in TI Clark

Additional Test site

	Current site	Additional site
Final Test site	TI Clark	TI CDAT

Applicable for devices with "*"

Qual details are provided in the Qual Data Section.
Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

Review the SDP for full evaluation of the change based on the customer use case.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
Amkor P1	AKR	PHL	Muntinlupa City

SCSAT	STS	SGP	Singapore
TI Clark	**QAB**	**PHL**	**Angeles City**

Sample Product Shipping Label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:

MSL 2 /260C/1 YEAR	SEAL DT
MSL 1 /235C/UNLIM	03/29/04

G4
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
~~(20L) CSO: SHE~~ (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

DS90HB983WRURRQ1	DS90UB688RURRQ1	DS90UB9742FTRURRQ1*
DS90HB983WRURTQ1	DS90UB688RURTQ1	DS90UB9742FTRURTQ1*
DS90HB984WRURRQ1	DS90UB944ARURRQ1	DS90UB9742TRURRQ1*
DS90HB984WRURTQ1	DS90UB944ARURTQ1	DS90UB9742TRURTQ1*
DS90UB1688RURRQ1	DS90UB9702TRURRQ1*	DS90UB984RURRQ1
DS90UB1688RURTQ1	DS90UB9702TRURTQ1*	DS90UB984RURTQ1
DS90UB1722TRURRQ1*	DS90UB9722TRURRQ1*	DS90UB988RURRQ1
DS90UB1722TRURTQ1*	DS90UB9722TRURTQ1*	DS90UB988RURTQ1
DS90UB1724TRURRQ1*	DS90UB9724FTRURRQ1*	DS90UH984RURRQ1
DS90UB1724TRURTQ1*	DS90UB9724FTRURTQ1*	DS90UH984RURTQ1
DS90UB1742TRURRQ1*	DS90UB9724SRURRQ1*	DS90UH988RURRQ1
DS90UB1742TRURTQ1*	DS90UB9724SRURTQ1*	DS90UH988RURTQ1
DS90UB3702TRURRQ1*	DS90UB9724TRURRQ1*	
DS90UB3702TRURTQ1*	DS90UB9724TRURTQ1*	

*TI CDAT as additional Test Site

Qualification Report

Automotive Qualification Summary
(As per AEC-Q100 Rev. J and JEDEC Guidelines)

Punch QFN Qual at Clark for 984 RUR (12x12mm) Packages

Approve Date 19-March-2026

Product Attributes

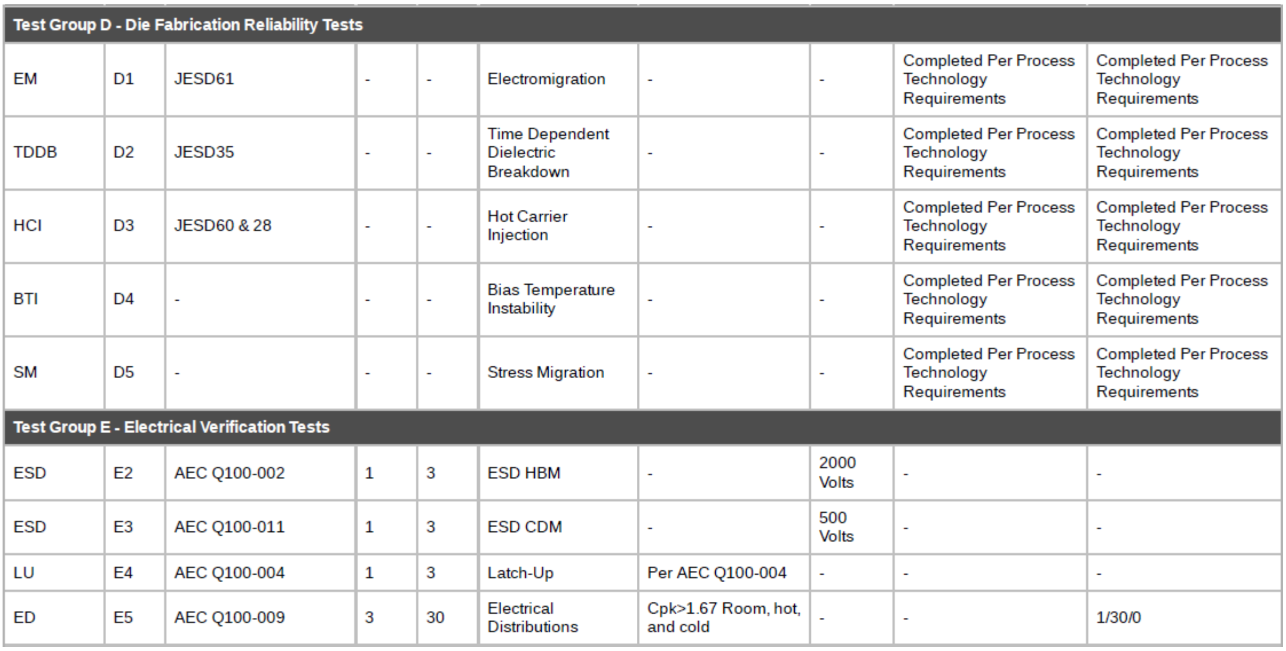
Attributes	Qual Device: DS90UH984RURTQ1	Qual Device: DS90UH984RURRQ1
Automotive Grade Level	Grade 2	Grade 2
Operating Temp Range (C)	-40 to 105	-40 to 105
Product Function	Signal Chain	Signal Chain
Wafer Fab Supplier	LFAB	DMOS6
Assembly Site	CLARK-AT	CLARK-AT
Package Group	QFN	QFN
Package Designator	RUR	RUR
Pin Count	88	88

QBS: Qual By Similarity, also known as Generic Data
Qual Device DS90UH984RURTQ1 is qualified at MSL3 260C
Qual Device DS90UH984RURRQ1 is qualified at MSL3 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: DS90UH984RURTQ1	Qual Device: DS90UH984RURRQ1
Test Group A - Accelerated Environment Stress Tests									
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	1/320/0	2/260/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	1/77/0	2/154/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	2/154/0
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	2/154/0
TC-BP	A4	MIL-STD883 Method 2011	1	5	Post Temp Cycle Bond Pull	-	-	1/5/0	1/5/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	500 Hours	1/45/0	2/90/0
Test Group B - Accelerated Lifetime Simulation Tests									
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	1/77/0	-
Test Group C - Package Assembly Integrity Tests									
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	2/60/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	2/60/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	2/20/0



Test Group D - Die Fabrication Reliability Tests									
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
TDDB	D2	JESD35	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements	Completed Per Process Technology Requirements
Test Group E - Electrical Verification Tests									
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	-	-
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	-	-
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	-	-
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	-	1/30/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Ambient Operating Temperature by Automotive Grade Level:

Grade 0 (or E): -40C to +150C
Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2507-035

Qualification Report
Automotive Qualification Summary
(As per AEC and JEDEC Guidelines)

Q006 QFN at TI Clark
Approve Date 19-March-2026

Product Attributes

Attributes	Qual Device: DS90UH984RURTQ1	Qual Device: DS90UH984RURRQ1
Automotive Grade Level	Grade 2	Grade 2
Operating Temp Range (C)	-40 to 105	-40 to 105
Product Function	Signal Chain	Signal Chain
Wafer Fab Supplier	LFAB	DMOS6
Assembly Site	CLARK-AT	CLARK-AT
Package Group	QFN	QFN
Package Designator	RUR	RUR
Pin Count	88	88

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: DS90UH984RURTQ1	Qual Device: DS90UH984RURRQ1
Test Group A - Accelerated Environment Stress Tests									
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL3 260C	-	1/320/0	2/260/0
PC	A1.1	-	3	22	SAM Precon Pre	Review for delamination	-	1/22/0	2/44/0
PC	A1.2	-	3	22	SAM Precon Post	Review for delamination	-	1/22/0	2/44/0
HAST	A2.1	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	1/77/0	2/154/0
HAST	A2.2	JEDEC JESD22-A110	3	70	Biased HAST	130C/85%RH	192 Hours	1/77/0	2/154/0
TC	A4.1	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	2/154/0
TC	A4.1.1	-	3	22	SAM Analysis, post TC 1X	Review for delamination	Completed	1/22/0	2/44/0
TC	A4.2	JEDEC JESD22-A104 and Appendix 3	3	70	Temperature Cycle	-65C/150C	1000 Cycles	1/77/0	2/154/0
HTSL	A6.1	JEDEC JESD22-A103	3	45	High Temperature Storage Life	150C	500 Hours	1/45/0	2/90/0
HTSL	A6.2	JEDEC JESD22-A103	3	44	High Temperature Storage Life	150C	1000 Hours	1/45/0	2/90/0
Test Group C - Package Assembly Integrity Tests									
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	2/60/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	2/60/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device DS90UH984RURTQ1 is qualified at MSL3 260C
Qual Device DS90UH984RURRQ1 is qualified at MSL3 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Ambient Operating Temperature by Automotive Grade Level:
Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C
Grade 2 (or T): -40C to +105C
Grade 3 (or I) : -40C to +85C
E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):
Room/Hot/Cold : HTOL, ED
Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU
Room : AC/uHAST
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2507-035

ZVEI ID: SEM-PA-18, SEM-PA-07, SEM-PA-05, SEM-TF-01

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a ‘product qualification family’ for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled “QBS Process” (for wafer fab process), “QBS Package” (for assembly process) and “QBS Product” (for product family).

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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